

**IN THE SPECIFICATION**

Page 1, before the first line, add the paragraph:

This is a continuation application of U.S. Serial No. 10/108,439, filed March 29, 2002, <sup>now Patent No. 6,667,193</sup> ~~(now allowed)~~, which is a continuation application of U.S. Serial No. 10/108,483, filed March 29, 2002 (now U.S. Patent No. 6,590,276), which is a continuation application of U.S. Serial No. 09/733,929, filed December 12, 2000 (now U.S. Patent No. 6,399,423).

Page 1, line 7, replace line with:

~~BACKGROUND OF THE INVENTION~~ FIELD OF THE INVENTION

Page 1, between lines 12 and 13, add the line:

DESCRIPTION OF THE RELATED ART

**IN THE ABSTRACT**

~~To improve the connection reliability at the time of packaging a semiconductor device and to make the method management easy in a semiconductor device manufacturing method.~~

The semiconductor device comprises: a tube for supporting a semiconductor chip 2; a sealing body 3 formed by sealing the semiconductor chip 2 with a resin; a plurality of leads made of a copper alloy, exposed to the back face 3a of